

AMENDMENTS TO THE ABSTRACT

Please amend the Abstract as follows:

~~The present invention discloses a~~ A light emitting device package, ~~comprising~~ includes a metal ~~base;~~ base, an electrical circuit layer provided at an upper side of the metal base for providing a conductive ~~path;~~ path, a light emitting device mounted in a second region having a smaller thickness than a first region on the metal ~~base;~~ base, an insulating layer sandwiched between the ~~meta-metal~~ base and the electrical circuit ~~layer;~~ layer, an electrode layer provided at an upper side of the electrical circuit ~~layer;~~ layer, and a wire for electrically connecting the electrode layer and the light emitting device. ~~Further, there is provided a~~ The light emitting device package ~~which is improved in~~ has improved light emission efficiency since the light emitting device is placed on a small thickness portion of the metal base.